

**LISTING OF THE CLAIMS:**

1. (Currently Amended) An electronic device, comprising:
  - a semiconductor chip having a first surface in electrical communication with a substrate;
  - a heat spreader being arrayed in closely spaced relationship with an opposite surface of said semiconductor chip, said heat spreader being constituted of a heat-absorbing and dissipating material; and
  - adhesive means bonding said heat spreader to said semiconductor chip, said adhesive means comprising an electrically conductive silicone adhesive positioned in an essentially single spot on a center or an areal surface portion of said semiconductor chip, wherein said electrically conductive adhesive is deposited on the areal surface portion of said semiconductor chip surface to form an about 1 mm diameter bond area with said heat spreader, said electrically conductive silicone adhesive electrically connecting said heat spreader with said semiconductor chip, and an electrically non-conductive silicone adhesive of an extensively larger surface area than said single spot formed by said electrically conductive silicone adhesive essentially consisting of a thermally conductive adhesive for conveying heat from said semiconductor chip to said heat spreader and extending about said electrically conductive silicone adhesive and extending into proximity with the edges of said ~~heat spreader~~ semiconductor chip for concurrently bonding said heat spreader to said semiconductor chip.

2. (Currently Amended) An electronic device, as claimed in Claim 1, wherein said heat spreader comprises an electrically conductive material forming an said electrical connection with said semiconductor chip through said electrically conductive adhesive.

Claim 3 (Cancelled).

4. (Original) An electronic device, as claimed in Claim 2, wherein said heat spreader is selected from the group of materials consisting of copper, silver, aluminum, alumina or alumina silica carbide.

5. (Original) An electronic device, as claimed in Claim 1, wherein said heat spreader comprises a plate-shaped lid or cap member adhesively bonded to said semiconductor chip.

Claim 6 (Cancelled).

Claims 7 and 8 (Cancelled).

9. (Currently Amended) An electronic device, as claimed in Claim 1, wherein said electrically non-conductive adhesive is deposited on said semiconductor chip so as to cover essentially a major portion of the remaining surface area of said chip extending about said electrically conductive adhesive.

10. (Previously Presented) An electronic device, as claimed in Claim 1, wherein said heat spreader is spaced from said semiconductor chip to provide a bondline thickness of about 0.025 mm to 0.15 mm for said adhesives.

11. (Currently Amended) A method of forming an electronic device, said method comprising:

providing a semiconductor chip having a first surface in electrical communication with a substrate;

arranging a heat spreader in closely spaced relationship with an opposite surface of said semiconductor chip, said heat spreader being constituted of a heat-absorbing and dissipating material; and

having adhesive means bond said heat spreader to said semiconductor chip, said adhesive means comprising an electrically conductive silicone adhesive positioned in an essentially single spot formed by said electrically conductive silicone adhesive on a center or an areal surface portion of said semiconductor chip, wherein said electrically conductive adhesive is deposited on the areal surface portion of said semiconductor chip surface to form an about 1 mm diameter bond area with said heat spreader, said electrically conductive silicone adhesive electrically connecting said heat spreader with said semiconductor chip, and an electrically non-conductive silicone adhesive essentially consisting of a thermally conductive adhesive for conveying heat from said semiconductor chip to said heat spreader and of an extensively larger surface area than said single spot extending about said electrically conductive silicone adhesive and extending into proximity with the edges of said heat

spreader semiconductor chip for concurrently bonding said heat spreader to said semiconductor chip.

12. (Currently Amended) A method, as claimed in Claim 11, wherein said heat spreader comprises an electrically conductive material forming an said electrical connection with said semiconductor chip through said electrically conductive adhesive.

Claim 13 (Cancelled).

14. (Original) A method, as claimed in Claim 12, wherein said heat spreader is selected from the group of materials consisting of copper, silver, aluminum, alumina or alumina silica carbide.

15. (Original) A method, as claimed in Claim 11, wherein said heat spreader comprises a plate-shaped lid or cap member adhesively bonded to said semiconductor chip.

Claim 16 (Cancelled).

Claims 17 and 18 (Cancelled).

19. (Currently Amended) A method, as claimed in Claim 11, wherein said electrically non-conductive adhesive is deposited on said semiconductor chip so as to cover essentially a major portion of the remaining surface area of said chip extending about said electrically conductive adhesive.
20. (Previously Presented) A method, as claimed in Claim 11, wherein said heat spreader is spaced from said semiconductor chip to provide a bondline thickness of about 0.025 mm to 0.15 mm for said adhesives.